

Docket No. 650.00713COMMISSIONER FOR PATENTS  
Washington D.C. 20231

Sir:

10/26/01COPY OF PAPERS  
ORIGINALLY FILED868 U.S. PRO  
10/055169  
10/26/01

Transmitted herewith for filing is the patent application of:

Inventor: HIROHIDE ENAMI et al

For: THERMOPLASTIC ELASTOMER COMPOSITION FOR A POWDER FOR SLUSH MOLDING &amp; SKIN FORMED THEREFROM

Enclosed are:

1 sheets of drawing.

An assignment of the invention to \_\_\_\_\_.

A certified copy of a \_\_\_\_\_ application.

An associate power of attorney.

Small Entity Status: Applicant claims small entity status.

Information Disclosure Statement

The filing fee has been calculated as shown below:

| (Col. 1)                           | (Col. 2)        |
|------------------------------------|-----------------|
| FOR:                               | NO. FILED       |
| BASIC FEE                          |                 |
| TOTAL CLAIMS                       | 109 - 20 = * 89 |
| INDEP. CLAIMS                      | 2 - 3 = * 0     |
| MULTIPLE DEPENDENT CLAIM PRESENTED |                 |

| SMALL ENTITY |        | OTHER THAN A SMALL ENTITY |        |
|--------------|--------|---------------------------|--------|
| RATE         | FEE    | RATE                      | FEE    |
|              | \$ 370 |                           | \$ 740 |
| x 9 =        |        | x 18 =                    | 1602   |
| x 42 =       |        | x 84 =                    |        |
| +140 =       |        | +280 =                    | 280    |
| TOTAL        |        | OR TOTAL                  | 2622   |

\*If the difference in Col. 1 is less than zero, enter 0 in Col. 2.

Please charge my Deposit Account No. 23-0785 amount of \$ \_\_\_\_\_ . A duplicate copy of this sheet is enclosed.

A check in the amount of \$ 2622.00 to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 23-0785. A duplicate copy of this sheet is enclosed.

- Any additional filing fees required under 37 CFR 1.16.
- Any patent application processing fees under 37 CFR 1.17.

The Commissioner is hereby authorized to charge payment of the following fees during the pendency of this application or credit any overpayment to Deposit Account No. 23-0785. A duplicate copy of this sheet is enclosed.

- Any patent application processing fees under 37 CFR 1.17.
- The issue fee set in 37 CFR 1.18 at or before mailing of the Notice of Allowance, pursuant to 37 CFR 1.311(b).
- Any filing fees under 37 CFR 1.16 for presentation of extra claims.

Respectfully submitted,

## CERTIFICATE OF MAILING BY "EXPRESS MAIL"

"Express Mail" mailing label number EM258140673  
Date of Deposit 10-26-01

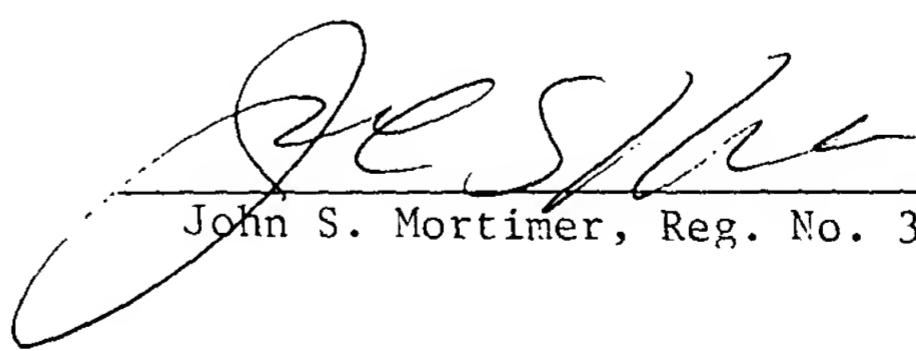
I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

T. Crane

(Typed or printed name of person mailing paper or fee)

T. Crane

(Signature of person mailing paper or fee)



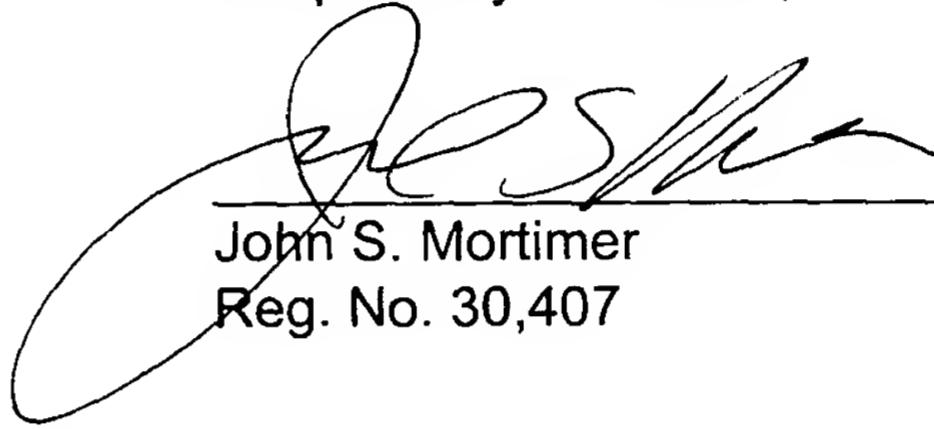
John S. Mortimer, Reg. No. 30,407

This application claims the priority of Japanese Application Nos. 331886/2000 filed October 31, 2000, 51764/2001 filed February 27, 2001, and 192147/2001 filed June 26, 2001.

Any additional costs incurred with regard to this matter should be charged to our Deposit Account No. 23-0785.

A filing date based on the filing of these papers under 37 CFR Section 1.10(a) is respectfully requested.

Respectfully submitted,



John S. Mortimer  
Reg. No. 30,407

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Oct 26, 2001

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21-25-02 A

COPY OF PAPERS  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: ) THERMOPLASTIC ELASTOMER COMPO-  
HIROHIDE ENAMI et al ) SITION FOR A POWDER FOR SLUSH  
                        ) MOLDING AND SKIN FORMED  
                        ) THEREFROM  
Ser. No.: Unassigned )  
                        )  
Filed: Herewith      )

TRANSMITTAL LETTER

Assistant Commissioner for Patents  
Washington, D.C. 20231  
Sir:

Enclosed herewith for filing under 37 C.F.R. Section 1.53(b) is a patent application, including:

- 1) A Specification and claims for the patent application of HIROHIDE ENAMI, KENROU ONO, KENJI KUBOMOTO, AND YOSHIHIRO TODA, entitled "THERMOPLASTIC ELASTOMER COMPOSITION FOR A POWDER FOR SLUSH MOLDING AND SKIN FORMED THEREFROM";
- 2) 1 sheet of formal drawings;
- 3) A check in the amount of \$2622.00 for the filing fee;
- 4) Computation sheet form PTO-1082;
- 5) Information Disclosure Statement and 4 References; and
- 6) Certificate of Mailing by "Express Mail"  
No. EM258140673 dated 10-26-01.

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Washington, DC 20231.

Terri Craine  
(Terri Craine)